



October 22, 2024

To,
BSE Limited
Phiroze Jejeebhoy Towers,
Dalal Street,
Mumbai – 400 001

Scrip Code: 543971

Dear Sir/Madam,

Sub: Outcome of the meeting of the Board of Directors of Bondada Engineering Limited (“Company”) held on Tuesday, October 22, 2024

Ref.: Regulation 30 of the Securities and Exchange Board of India (Listing Obligations and Disclosure Requirements) Regulations, 2015 (“SEBI LODR Regulations”)

Further to our intimation dated October 17, 2024 under Regulation 29 and in accordance with provisions of Regulation 30 read with Schedule III of the SEBI LODR Regulations, we would like to inform you that the board of directors of the Company (“**Board**”) at its meeting held today *i.e.*, Tuesday, October 22, 2024, has *inter-alia* considered and approved the following matters:

Consider and approve a proposal for raising of funds by way of issuance of equity shares or any other eligible securities of the Company, including debentures / non-convertible debt instruments along with warrants / convertible debentures / securities and / or any other equity based instruments, in one or more tranches, through one or more public and/or private offerings, including by way of a preferential issue, qualified institutions placement and/or any other method, as may be decided by the Board, subject to such statutory/ regulatory approvals as may be applicable including the approval of shareholders of the Company wherever required, for an aggregate amount upto Rs. 500 Cr.

The Board has also constituted fund raising committee and empowered them with all the authorities and powers with respect to fund raising exercise as specified above.

The information in connection with the issuance of securities pursuant to Regulation 30 of the SEBI LODR Regulations read with SEBI Circular No. SEBI/HO/CFD/CFD-PoD-1/P/CIR/2023/123 dated July 13, 2023, is enclosed as **Annexure A**.

The meeting of the Board of directors of the Company commenced at 5.00 p.m. and concluded at 7.20 p.m.

Bondada Engineering Limited
(Formerly known as Bondada Engineering Pvt Ltd)

Regd. Office:
Plot No-37, Ashok Manoj Nagar,
Kapra, Hyderabad, Telangana-500062,
Indian

Corporate Office:
BONDADA HOUSE,
C-26, Kushaiguda Industrial
Area, Kushaiguda, ECIL,
Hyderabad,
TG-500062

Phone Number: 7207034662

CIN : U28910TG2012PLC080018 **Email :** Info@bondada.net, **Website :** www.bondada.net



The disclosures along with the enclosures shall be made available on the website of the Company at www.bondada.net.

Kindly take the same on record of your esteemed Exchange and disseminate it on your website.

Thanking you,

Yours faithfully,

For, Bondada Engineering Limited

Sonia Bidlan
Company Secretary & Compliance officer
M. No- A37766

Place: Hyderabad

Encl.: As above.

Bondada Engineering Limited
(Formerly known as Bondada Engineering Pvt Ltd)

Regd. Office:

Plot No-37, Ashok Manoj Nagar,
Kapra, Hyderabad, Telangana-500062,
Indian

Corporate Office:

BONDADA HOUSE,
C-26, Kushaiguda Industrial
Area, Kushaiguda, ECIL,
Hyderabad,
TG-500062

Phone Number: 7207034662

CIN : U28910TG2012PLC080018 **Email** : Info@bondada.net, **Website** : www.bondada.net



Annexure - A – Details of Preferential Issue

DISCLOSURE PURSUANT TO PARAGRAPH 2 OF PART A, SCHEDULE III OF THE SEBI LODR REGULATIONS READ WITH THE SEBI/HO/CFD/CFD-POD-1/P/CIR/2023/123 DATED JULY 13, 2023.

Sr. No.	Particulars	Disclosure
1.	Types of securities proposed to be issued	Equity shares or debentures any combination thereof and/or security convertible into equity shares;
2.	Type of issuance	To be decided by fund raising committee
3.	The total amount for which the securities will be issued (approximately)	For an aggregate consideration of up to ₹ 500 Crores
4.	In case of preferential issue, the listed entity shall disclose the following additional details to the stock exchange(s)	Not Applicable
5.	In case of bonus issue the listed entity shall disclose the following additional details to the stock exchange(s)	
6.	In case of issuance of depository receipts (ADR/GDR) or FCCB the listed entity shall disclose following additional details to the stock exchange(s)	
7.	In case of issuance of debt securities or other nonconvertible securities the listed entity shall disclose following additional details to the stock exchange(s)	
8.	Any cancellation or termination of proposal for issuance of securities including reasons thereof	

Thanking You,
For, Bondada Engineering Limited

Sonia Bidlan
Company Secretary & Compliance officer
M. No- A37766
Place: Hyderabad

Bondada Engineering Limited
(Formerly known as Bondada Engineering Pvt Ltd)

Regd. Office:
Plot No-37, Ashok Manoj Nagar,
Kapra, Hyderabad, Telangana-500062,
Indian

Corporate Office:
BONDADA HOUSE,
C-26, Kushaiguda Industrial
Area, Kushaiguda, ECIL,
Hyderabad,
TG-500062
Phone Number: 7207034662

CIN : U28910TG2012PLC080018 Email : Info@bondada.net, Website : www.bondada.net